

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
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EPAS ID: PAT2996248

SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	
CONVEYING PARTY DATA		
	Name	Execution Date
	AI-HUA LIANG	10/22/2013
RECEIVING PARTY DATA		
Name:	SHUNSIN TECHNOLOGY (ZHONG SHAN) LIMITED	
Street Address:	No.9 JianYe East Road,,Zhongshan Torch Development Zone	
City:	Zhongshan	
State/Country:	CHINA	
PROPERTY NUMBERS Total: 1		
	Property Type	Number
	Application Number:	14061927
CORRESPONDENCE DATA		
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ATTORNEY DOCKET NUMBER:	US43821	
NAME OF SUBMITTER:	ZHIGANG MA	
SIGNATURE:	/Zhigang Ma/	
DATE SIGNED:	08/26/2014	
Total Attachments: 2		
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ASSIGNMENT

In consideration of value received, the receipt and sufficiency of which are hereby acknowledged, the undersigned ASSIGNOR(S)

1. AI-HUA LIANG, residing at Zhongshan, Guangdong, China
2. _____, residing at _____
3. _____, residing at _____
4. _____, residing at _____
5. _____, residing at _____
6. _____, residing at _____
7. _____, residing at _____

hereby sell(s), assign(s) and transfer(s) unto: **AMBIT MICROSYSTEMS (ZHONGSHAN) LTD.** having a principal place of business at **Zhongshan Torch Hi-tech Development Zone Zhongshan City, Guangdong Province, P.R.C.** hereafter designated "ASSIGNEE" the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100, in the invention and all patent applications including any and all divisions, continuations, substitutes, and reissues thereof, and all resulting patents, known as **PRINTED CIRCUIT BOARD WITH SHALLOW SOLDER PAD AND METHOD FOR MANUFACTURING THE SAME** for which the undersigned

[] previously executed --- Ser. No. _____ and filing date of _____
[x] is executing concurrently herewith

an application for Letters Patent of United States of America

AND the undersigned hereby authorize(s) and request(s) the United States Commissioner of Patents and Trademarks to issue said Letters Patent to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agree(s) that the attorneys of record in said application, if any, shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agree(s) to testify and execute any papers for ASSIGNEE, its successors, assigns and legal representatives, deemed essential by ASSIGNEE to ASSIGNEE's full protection and title in and to the invention hereby transferred.

Oct. 22. 2013
Date

Date _____

Date _____

Date _____

Date _____

Date _____

Date _____

Date _____